

# 50V, 200mA, Low-I<sub>Q</sub> 30μA Low-Dropout Linear Regulator with Enable

#### **DESCRIPTION**

The TQL821CSV50 is a high-performance low dropout linear voltage regulator for 5V with input range of 3V to 50V and low quiescent 30µA. TQL821CSV50 provides 2% output voltage accuracy and 200mA maximum driving current and is suitable for automotive or other supply systems.

TQL821CSV50 just requires one small ceramic capacitor of  $1\mu F$  to exhibit fast regulation and good stability. And it shows very low dropout voltage with 70mV in 100mA-load and 110mV in 200mA-load. The start operating voltage is 3V which is suitable to cranking condition of automotive system.

The device has an enable function to switch ON and OFF for power dissipation. And other protection functions such as thermal-shutdown and current-limit are against immediate damage.

### **APPLICATION**

- Automotive Power Supply Systems
- General Power Supply applications

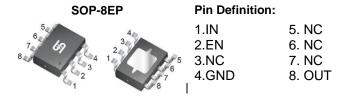
#### **FEATURES**

- AEC-Q100 qualified with the following results:
  - Device temperature grade 1: -40°C to 125°C
  - Device HBM ESD classification level H1C
  - Device CDM ESD classification level C3
- 3V to 50V Input Voltage Range
- 5V Fixed Output Voltage
- 70mV@100mA Low Dropout Voltage
- 200mA Output Current
- Typical 30µA Low Quiescent Current
- Typical ±2% Output Voltage Accuracy
- 1µF Ceramic Output Stable Capacitor
- Output Current Limit
- Over Temperature Protection
- RoHS Compliant
- Halogen-Free according to IEC 61249-2-21



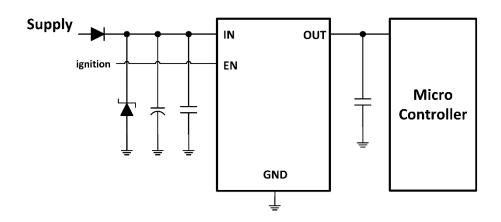






Notes: MSL 3 (Moisture Sensitivity Level) per J-STD-020

#### **TYPICAL APPLICATION CIRCUIT**



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ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise specified) (Note 1)				
PARAMETER	SYMBOL	LIMIT	UNIT	
Power Supply Pin	V <sub>IN</sub>	55	V	
EN Voltage to GND	V <sub>EN</sub>	-0.3 to 55	V	
OUT Voltage to GND	V <sub>OUT</sub>	-0.3 to 7	V	
Junction Temperature Range	TJ	-40 to +150	°C	
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C	
ESD Rating (Human Body Model) (Note 2)	HBM	±2	kV	
ESD Rating (Charged Device Model)	CDM	±1	kV	

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction to Case Thermal Resistance	Rejc	11	°C/W	
Junction to Ambient Thermal Resistance	RөJA	43	°C/W	

Notes: The thermal data is based on the PCB JESD 51-3 at natural convection on 1s0p board with 1 copper layer (1 x 70µm Cu) and with 300mm<sup>2</sup> heatsink area on PCB

RECOMMENDED OPERATING CONDITIONS (Note 3)				
PARAMETER	SYMBOL	CONDITIONS	UNIT	
Power Supply Pin	V <sub>IN</sub>	V <sub>OUT</sub> +V <sub>dr</sub> to 50	V	
Extended Power Supply Pin	V <sub>IN,ext</sub>	3 to 50	V	
EN Voltage to GND	V <sub>EN</sub>	0 to 50	V	
Output Stable Capacitor	Соит	≧1	μF	
ESR of Output Capacitor	ESR	≦100	Ω	
Operating Junction Temperature Range	TJ	-40 to +150	°C	
Operating Ambient Temperature Range	Тора	-40 to +125	°C	

<b>ELECTRICAL SPECIFICATIONS</b> (V <sub>IN</sub> = 13.5V, T <sub>J</sub> = -40 to 150°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Supply Voltage						
Output Voltage	0.05mA < I <sub>OUT</sub> < 200mA 5.44V < V <sub>IN</sub> < 28V	Vouт	4.9	5	5.1	V
Output Voltage	0.05mA < I <sub>OUT</sub> < 100mA 5.27V < V <sub>IN</sub> < 40V	V <sub>OUT</sub>	4.9	5	5.1	V
Start-up Slew-rate	$V_{IN} > 18V/ms$ $C_{OUT} = 1\mu F$ $0.5V < V_{OUT} < 4.5V$	dV <sub>оит</sub> /dt		35		V/ms
Current Limit	0V < V <sub>OUT</sub> < 4.8V	l <sub>lim</sub>		320		mA
Load Regulation	I <sub>OUT</sub> = 0.05 to 200mA V <sub>IN</sub> = 6V	$\Delta$ Vout,10	-15	-1.5	+15	mV



<b>ELECTRICAL SPECIFICATIONS</b> (V <sub>IN</sub> = 13.5V, T <sub>J</sub> = -40 to 150°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Supply Voltage						
Line Regulation	V <sub>IN</sub> = 8 to 32V I <sub>OUT</sub> = 1mA	$\Delta$ Vout,li	-20	0	20	mV
Dropout Voltage (V <sub>dr</sub> =V <sub>IN</sub> -V <sub>OUT</sub> )	I <sub>OUT</sub> = 200mA	$V_{dr}$		110	340	mV
Dropout Voltage (V <sub>dr</sub> =V <sub>IN</sub> -V <sub>OUT</sub> )	I <sub>OUT</sub> = 100mA	$V_{dr}$		70	170	mV
Power Supply Ripple Rejection	f = 100Hz, V = 0.5Vpp	PSRR		59		dB
Thermal Shutdown Threshold (Note 4)		T <sub>th</sub>	151		200	°C
Thermal Shutdown Hysteresis		T <sub>hy</sub>		30		°C
<b>Current Consumption</b>						
Standby Current (Io=I <sub>IN</sub> )	V <sub>EN</sub> = 0V, T <sub>J</sub> < 105°C	I <sub>O,st</sub>		1.3	5	μΑ
Standby Current (I <sub>O</sub> =I <sub>IN</sub> )	$V_{EN} = 0.4V, T_J < 125^{\circ}C$	$I_{O,st}$			8	μA
Quiescent Current (Io=IIN-IOUT)	I <sub>OUT</sub> = 0.05mA, T <sub>J</sub> = 25°C	lo		30	52	μA
Quiescent Current (Io=IIN-IOUT)	I <sub>OUT</sub> = 0.05mA, T <sub>J</sub> < 125°C	lo		62	77	μΑ
Enable	Enable					
High Level Input Voltage		VENH	2			V
Low Level Input Voltage	$V_{\text{OUT}} \leqq 0.1 V$	VENL			0.8	V
Threshold Hysteresis		$V_{ENHy}$	100			mV
EN Input Current	V <sub>EN</sub> = 3.3V	I <sub>EN</sub>			3.5	μA
EN Input Current	$V_{EN} \le 18V$	I <sub>EN</sub>			22	μA
EN Pull-down Resistor		R <sub>EN</sub>	0.95	1.5	2.6	mΩ

# Note:

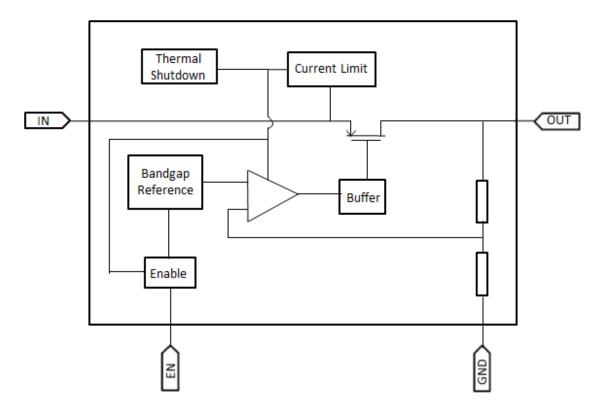
- Stresses listed as the above "Absolute Maximum Ratings" may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.
- 2. Devices are ESD sensitive. Handing precaution recommended.
- 3. The device is not guaranteed to function outside its operating conditions.
- 4. Guaranteed by design.

# **ORDERING INFORMATION**

ORDERING CODE	PACKAGE	PACKING
TQL821CSV50 RLG	SOP-8EP	2,500pcs / 13" Reel



# **BLOCK DIAGRAM**



# **PIN DESCRIPTION**

PIN NO.	NAME	FUNCTION
1	IN	Power supply pin for system
2	EN	Enable system function
3	NC	Not connected
4	GND	Ground
5	NC	Not connected
6	NC	Not connected
7	NC	Not connected
8	OUT	Output supply voltage
Pad		Connect to GND

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#### **APPLICATION INFORMATION**

TQL821CSV50 is a high performance low dropout voltage regulator. The device operates with a wide input voltage from 3V to 50V and up to 200mA of output current. It also provides a high accuracy output voltage for ±2% in all the load and line regulation.

### **Enable**

The EN pin is high voltage tolerant pin. High input enables the device ON and low is disable which can be connected to microcontroller or digital control system. It can be connected to input power pin directly.

### Thermal Shutdown (TSD)

Internal 160°C comparator will trigger temperature protection (TSD). TSD will shut down system, until internal temperature back to 130°C.

# **Current Limit**

The TQL821CSV50 features Current Limit function to protect device from damage by excessive power dissipation such as OUT shorted to GND. It limits output current to maintain power dissipation in the safe region.

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### **TYPICAL OPERATING CHARACTERISTICS**

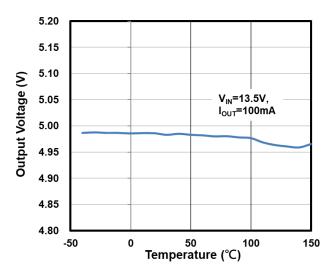


Figure 1. Output Voltage vs. Junction Temperature

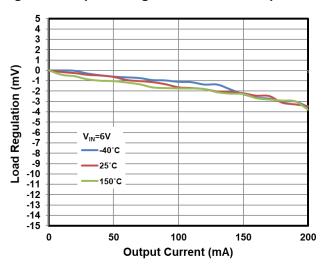


Figure 3. Load Regulation vs. Output Current

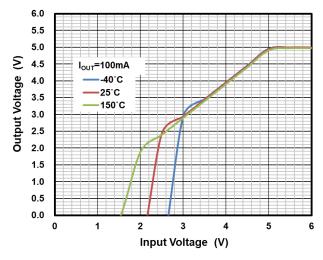


Figure 5. Output Voltage vs. Input Voltage

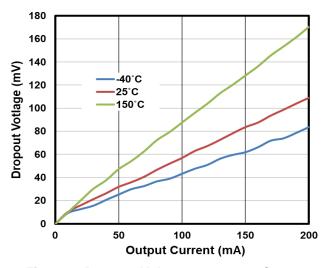


Figure 2. Dropout Voltage vs. Output Current

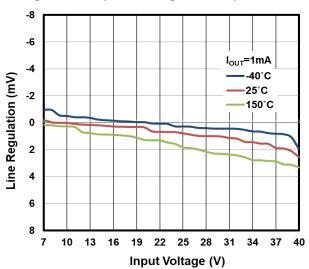


Figure 4. Line Regulation vs. Input Voltage

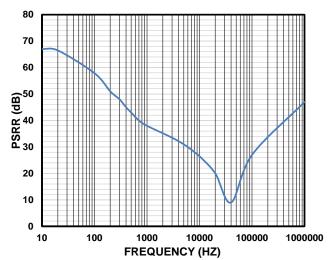


Figure 6. Ripple Rejection vs. Frequency



# **TYPICAL OPERATING CHARACTERISTICS (CONTINUE)**

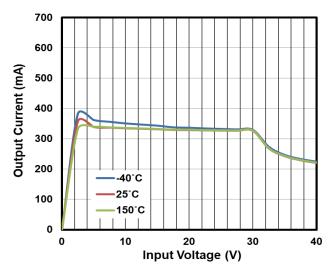


Figure 7. Output Current vs. Input Voltage

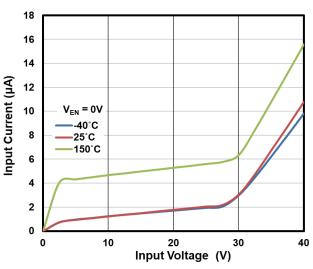


Figure 9. Input Current vs. Input Voltage

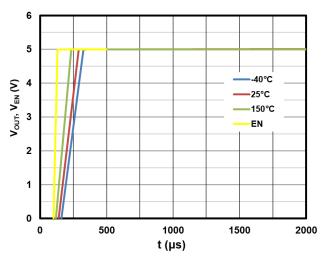


Figure 11. Output Voltage vs. time (EN switched ON)

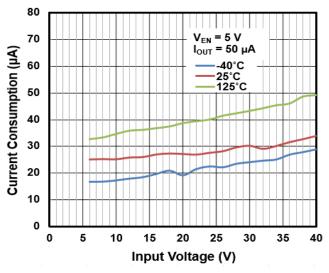


Figure 8. Current Consumption vs. Input Voltage

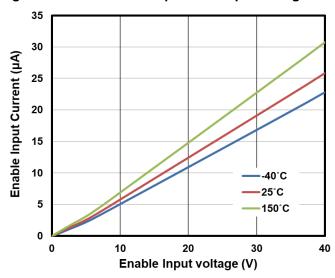


Figure 10. Enabled Input Current vs.

Enabled Input Voltage

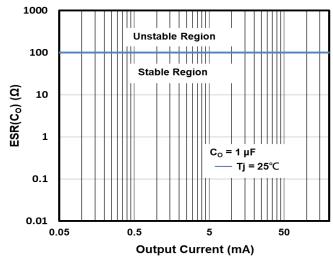


Figure 12. Output Capacitor Series Resistor ESR(C<sub>0</sub>) vs. Output Current

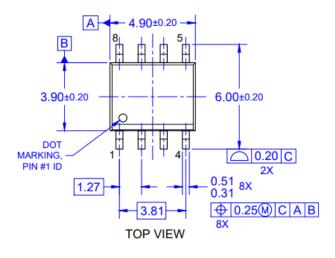
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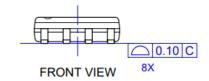
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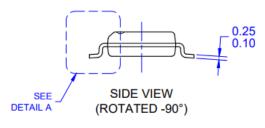


# **PACKAGE OUTLINE DIMENSIONS**

#### SOP-8EP









MARKING DIAGRAM

Y = Year Code

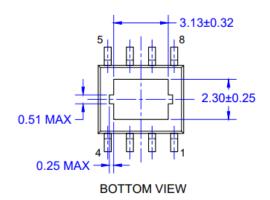
M = Month Code for Halogen Free Product

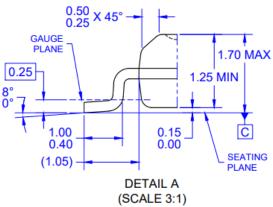
O =Jan P =Feb Q =Mar R =Apr

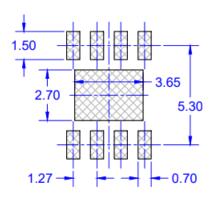
S = May T = Jun U = Jul V = Aug

W = Sep X = Oct Y = Nov Z = Dec

L = Lot Code (1~9, A~Z)







SUGGESTED PAD LAYOUT

#### NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC MS-012, ISSUE G, VARIATION BA.
- MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- 5. DWG NO REF: HQ2SD07-030 REV A.

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